







## Electrical Optical Characteristics at Ta=25°C

| Parameter                 | Symbol         | Min. | Typ. | Max. | Unit  | Test Condition                  |
|---------------------------|----------------|------|------|------|-------|---------------------------------|
| Radiant Intensity         | I <sub>e</sub> | 2.2  | 3.0  | 4.4  | mW/sr | I <sub>F</sub> =20mA (Note 1,3) |
| Viewing Angle             | $\frac{1}{2}$  | ---  | 130  | ---  | Deg.  | (Note 2)                        |
| Peak Wavelength           |                | ---  | 940  | ---  | nm    | I <sub>F</sub> =20mA            |
| Spectral Line Half- Width |                | ---  | 50   | ---  | nm    | I <sub>F</sub> =20mA            |
| Forward Voltage           | V <sub>F</sub> | ---  | 1.25 | 1.60 | V     | I <sub>F</sub> =50mA            |
| Reverse Current           | I <sub>R</sub> | ---  | ---  | 100  | μA    | V <sub>R</sub> =5V              |

### Note:

- Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- $\frac{1}{2}$  is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
- The I<sub>e</sub> guarantee should be added ±15% tolerance.

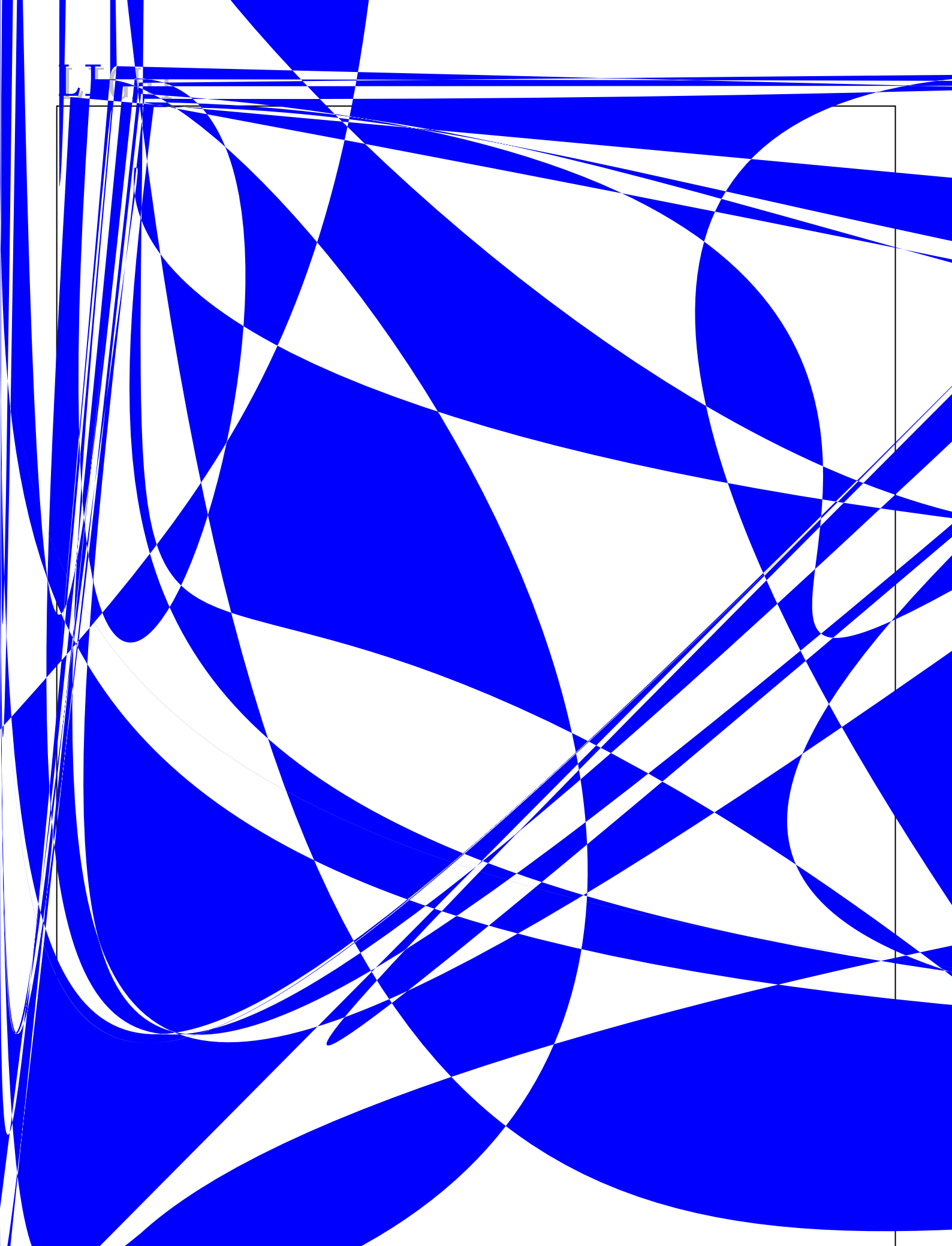
## Infrared Emitting Diode Specification

### ●Commodity: Infrared emitting diode

### ●Intensity Bin Limits (At 20mA)

| BIN CODE | Min. (mW/sr) | Max. (mW/sr) |
|----------|--------------|--------------|
| 18       | 2.2          | 2.6          |
| 19       | 2.6          | 3.1          |
| 20       | 3.1          | 3.7          |
| 21       | 3.7          | 4.4          |

NOTE: The I<sub>e</sub> guarantee should be added ±15% tolerance.





## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).





